

L Number	Hits	Search Text	DB	Time stamp
1	11	5309021.URPN.	USPAT	2004/07/09 10:38
2	5	("4612504" "4812949" "4949158" "5016084" "5057805").PN.	USPAT	2004/07/09 10:39
21	12	(257/666.ccls. and (@ad<19950508)) and (solder near (ball or balls))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 11:04
22	575	leadless and (@ad<19950508) and (encapsulation or encapsulant or mold or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 11:04
23	33	(leadless and (@ad<19950508) and (encapsulation or encapsulant or mold or epoxy)) and (solder near (ball or balls)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 11:04
-	1	("5677566").PN.	USPAT	2004/07/08 16:46
-	1	("20010013645").PN.	USPAT; US-PGPUB	2004/07/08 16:50
-	2204	257/666.ccls. and (@ad<19950508)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/08 16:52
-	535	(257/666.ccls. and (@ad<19950508)) and (encapsulation or encapsulant or mold or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 11:03
-	11	5309021.URPN.	USPAT	2004/07/08 18:14